

# DELTA X1 NO-CLEAN LOW RESIDUE PASTE FLUX

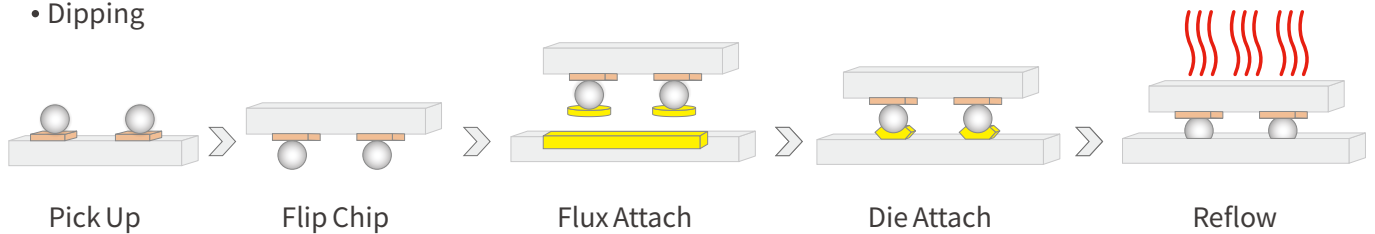
Delta X1 is a Zero-Halogen, No-Clean flip-chip dipping paste flux formulation especially designed for extremely low residue. Its unique characteristic delivers better adhesion for underfills, and reduces possible outgassing during curing.

## Main Features

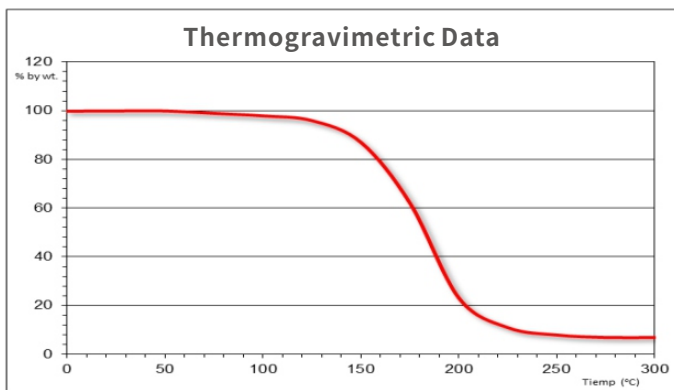


## Application

- Dipping



## Thermal Gravimetric Analysis (TGA)



## After Reflow Solder IMC



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## Typical Analysis

PROPERTIES	SPECIFICATIONS	METHOD
Flux Classification	ROLO	IPC-J-STD-004B
Appearance	Light Amber	Visual
pH - 5% Aqueous Solution	6 - 8	QIT
Halide Content	Halide - Free	IPC-TM-650 2.3.33 (Silver Chromate Test)
Halogen Content	Zero - Halogen	EN 14582
Malcom Viscosity (@10rpm)	25 - 55 Pa.s	IPC-TM-650 2.4.34.3 (Modified)
Tack Strength	100 - 200 gf	JIS Z 3284
Surface Insulation Resistance	$> 1.0 \times 10^9$ ohms	IPC-TM-650 2.6.3.3
Post Reflow Flux Residue	< 10%	TGA Analysis



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